

# DATA SHEET



## GaAs HBT INTEGRATED CIRCUIT

# μPG2318T5N

### 2.4 GHz SINGLE BAND POWER AMPLIFIER FOR W-LAN

#### DESCRIPTION

The μPG2318T5N is a GaAs HBT MMIC power amplifier for 2.4 GHz band wireless LAN.

This device realizes high efficiency, high gain and high output power by using InGaP HBT.

This device is housed in a 6-pin plastic TSON (Thin Small Out-line Non-leaded) package, and is suitable for high-density surface mounting.

#### FEATURES

- Operating frequency :  $f_{opt} = 2\ 400$  to  $2\ 500$  MHz (2 450 MHz TYP.)
- Supply voltage :  $V_{cc1, 2} = 3.0$  to  $4.6$  V (3.3 V TYP.)
- Control voltage :  $V_{enable} = 0$  to  $3.0$  V (2.8 V TYP.)
- Circuit current :  $I_{cc} = 120$  mA TYP. @  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  
 $P_{out} = +18$  dBm (at OFDM modulation : 64QAM/54 Mbps)
- Power gain :  $G_P = 28$  dB TYP. @  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  
 $P_{out} = +18$  dBm (at OFDM modulation : 64QAM/54 Mbps)
- Gain flatness :  $\Delta G_P = 0.8$  dB TYP. @  $f = 2.4$  to  $2.5$  GHz,  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  
 $P_{out} = +18$  dBm (at OFDM modulation : 64QAM/54 Mbps)
- Error vector magnitude :  $EVM = 2.5\%$  TYP. @  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  
 $P_{out} = +18$  dBm (at OFDM modulation : 64QAM/54 Mbps)
- Harmonics :  $2f_0 = 30$  dBc TYP. @  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  
 $P_{out} = +18$  dBm (at OFDM modulation : 64QAM/54 Mbps)
- High-density surface mounting : 6-pin plastic TSON package ( $1.5 \times 1.5 \times 0.37$  mm)

#### APPLICATIONS

- Power Amplifier for 802.11b/g
- 2.4 GHz ISM Band Transceivers

#### ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2318T5N-E2	μPG2318T5N-E2-A	6-pin plastic TSON (Pb-Free)	G5G	<ul style="list-style-type: none"><li>• Embossed tape 8 mm wide</li><li>• Pin 1, 6 face the perforation side of the tape</li><li>• Qty 3 kpcs/reel</li></ul>

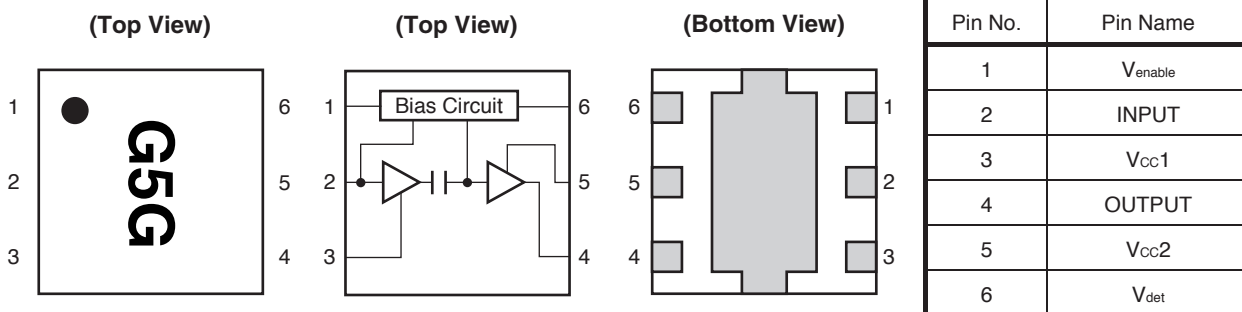
**Remark** To order evaluation samples, contact your nearby sales office.

Part number for sample order: μPG2318T5N-A

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

**PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM**



**Remark** Exposed pad : GND

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = +25°C, unless otherwise specified)**

Parameter	Symbol	Ratings	Unit
Supply Voltage	V <sub>cc1, 2</sub>	5.0	V
Control Voltage	V <sub>enable</sub>	4.0	V
Input Power	P <sub>in</sub>	+10	dBm
Power Dissipation	P <sub>D</sub>	500 <sup>Note</sup>	mW
Operating Ambient Temperature	T <sub>A</sub>	-45 to +85	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

**Note** Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB, T<sub>A</sub> = +85°C

**RECOMMENDED OPERATING RANGE (T<sub>A</sub> = +25°C, unless otherwise specified)**

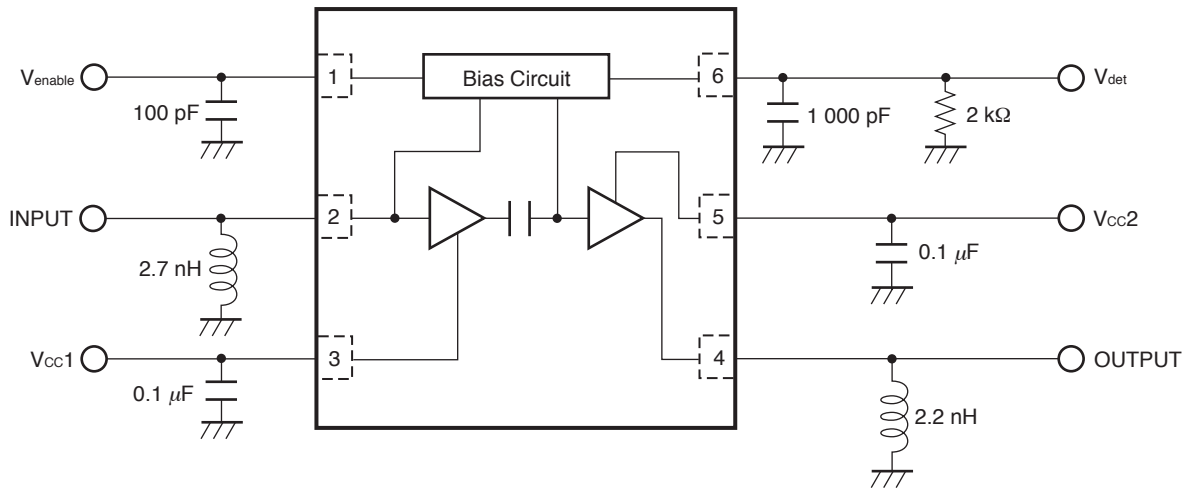
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f <sub>opt</sub>	2 400	2 450	2 500	MHz
Supply Voltage	V <sub>cc1, 2</sub>	3.0	3.3	4.6	V
Control Voltage	V <sub>enable</sub>	0	2.8	3.0	V

**ELECTRICAL CHARACTERISTICS**

( $T_A = +25^\circ\text{C}$ ,  $f = 2\ 400$  to  $2\ 500$  MHz, OFDM modulation : 64QAM/54 Mbps,  $V_{cc1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V, external input and output matching, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	$I_{CC}$	$P_{out} = +18$ dBm	-	120	140	mA
Power Gain	$G_P$	$P_{out} = +18$ dBm	25.5	28	-	dB
Gain Flatness	$\Delta G_P$	$P_{out} = +18$ dBm	-	0.8	1.3	dB
Control Current	$I_{enable}$	$P_{out} = +18$ dBm	-	3.2	-	mA
Error Vector Magnitude	EVM	$P_{out} = +18$ dBm	-	2.5	-	%
Input Return Loss	$RL_{in}$	$P_{out} = -30$ dBm (no-modulation)	-	15	-	dB
Output Return Loss	$RL_{out}$	$P_{out} = -30$ dBm (no-modulation)	-	5	-	dB
2nd Harmonics	$2f_0$	$P_{out} = +18$ dBm	-	30	-	dBc
3rd Harmonics	$3f_0$	$P_{out} = +18$ dBm	-	48	-	dBc
Power Detector Voltage	$V_{det}$	$P_{out} = +18$ dBm	-	0.7	-	V

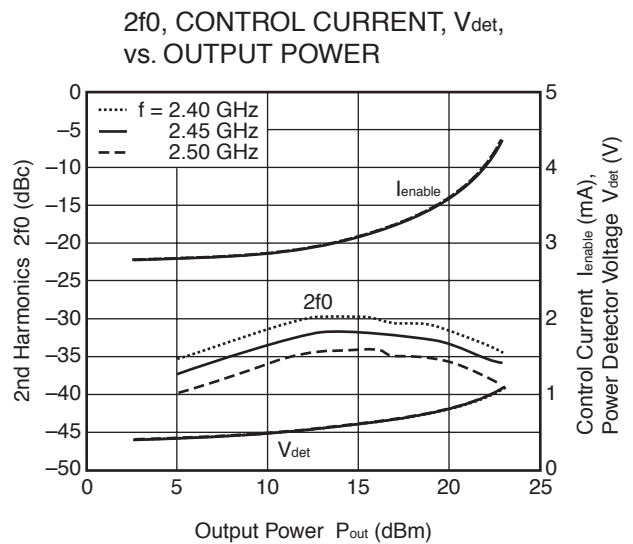
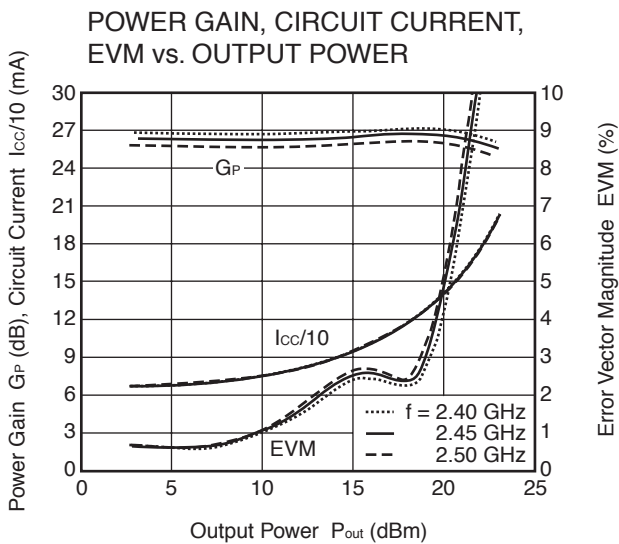
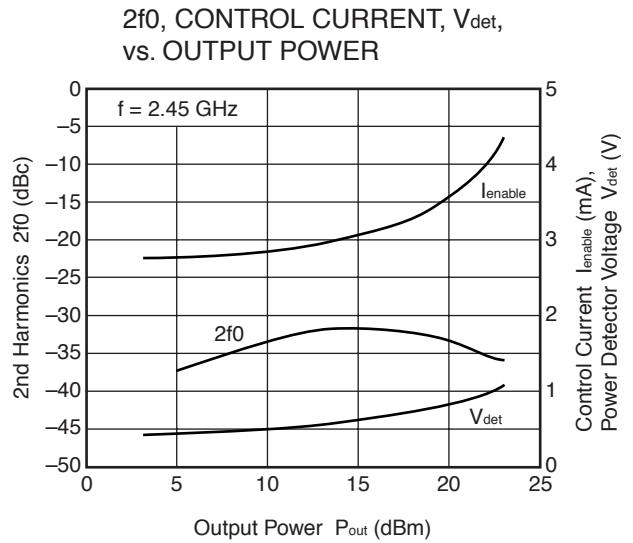
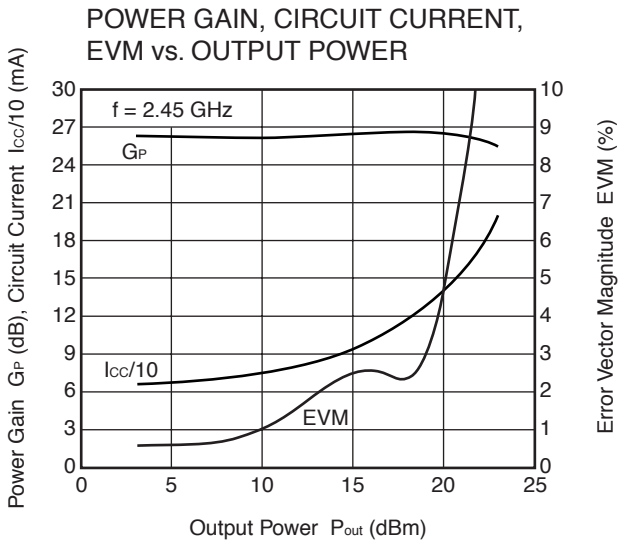
<R> EVALUATION CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

**TYPICAL CHARACTERISTICS 1**

( $T_A = +25^\circ\text{C}$ ,  $V_{CC1, 2} = 3.3\text{ V}$ ,  $V_{enable} = 2.8\text{ V}$ , OFDM modulated signal : 64QAM/54 Mbps, with external input and output matching circuits, unless otherwise specified)

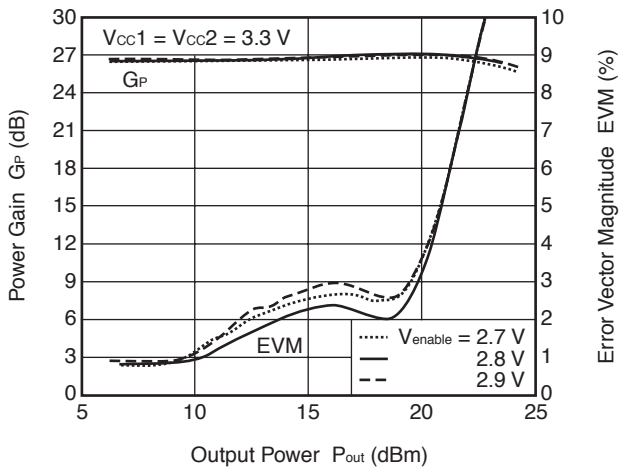


**Remark** The graphs indicate nominal characteristics.

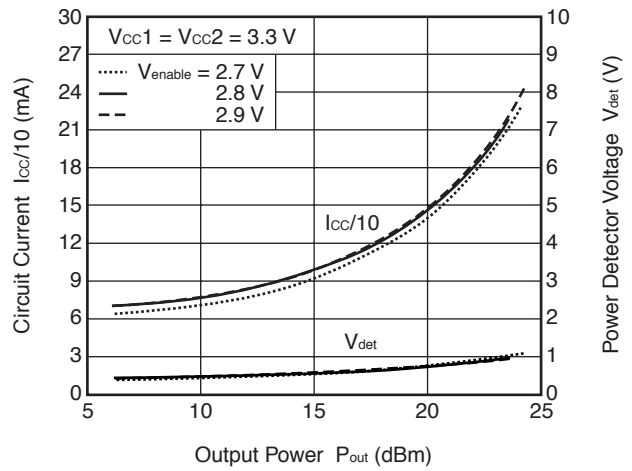
**TYPICAL CHARACTERISTICS 2**

( $T_A = +25^\circ\text{C}$ ,  $f = 2.45\text{ GHz}$ , OFDM modulated signal : 64QAM/54 Mbps, with external input and output matching circuits, unless otherwise specified)

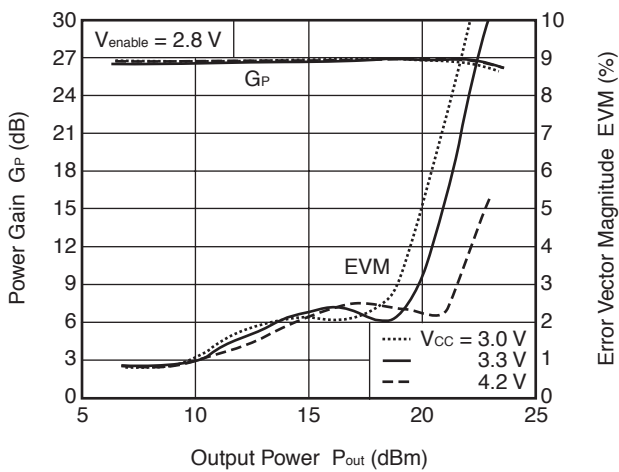
**POWER GAIN, EVM vs. OUTPUT POWER**



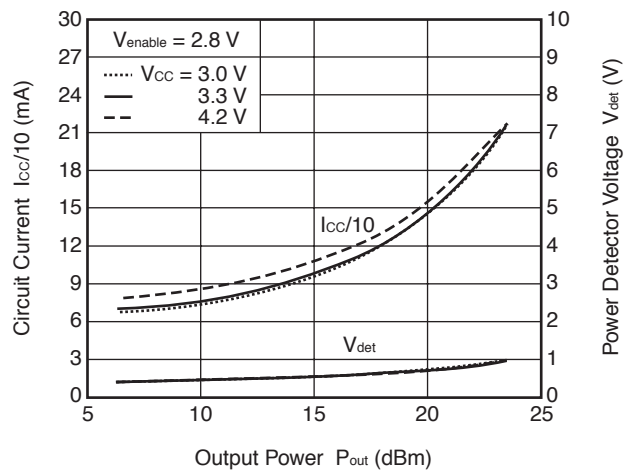
**CIRCUIT CURRENT,  $V_{det}$ , vs. OUTPUT POWER**



**POWER GAIN, EVM vs. OUTPUT POWER**



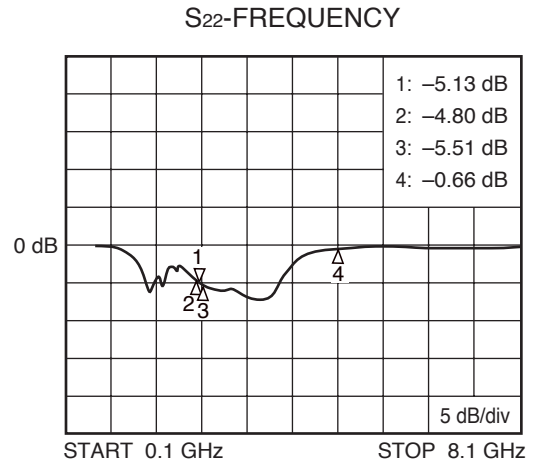
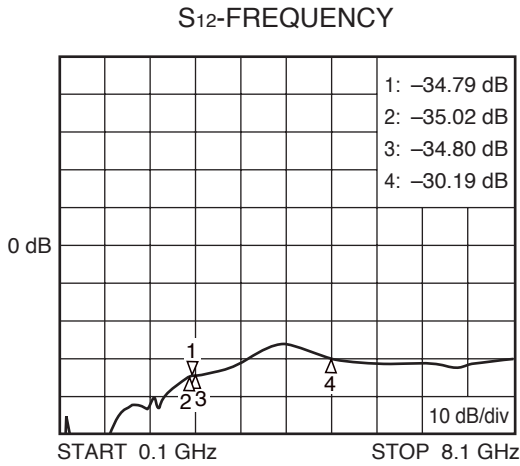
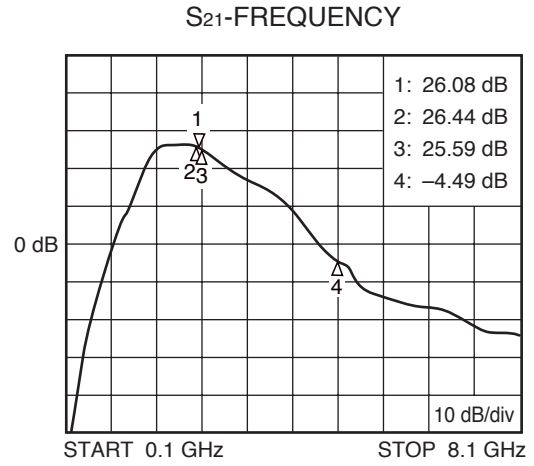
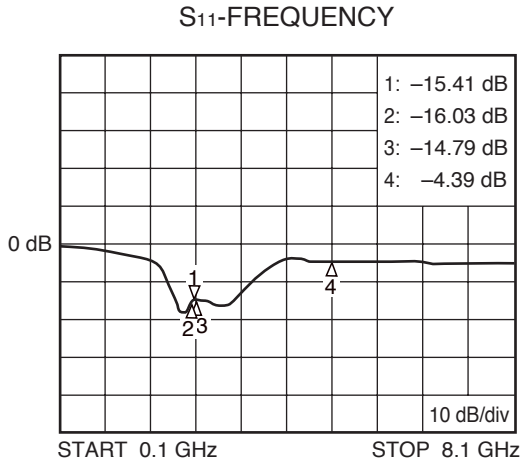
**CIRCUIT CURRENT,  $V_{det}$ , vs. OUTPUT POWER**



**Remark** The graphs indicate nominal characteristics.

<R> **S-PARAMETERS (Reference Data) –This data is included external matching components–**

Condition :  $T_A = +25^\circ\text{C}$ ,  $f = 0.1$  to  $8.1$  GHz,  $V_{CC1, 2} = 3.3$  V,  $V_{enable} = 2.8$  V,  $P_{in} = -30$  dBm



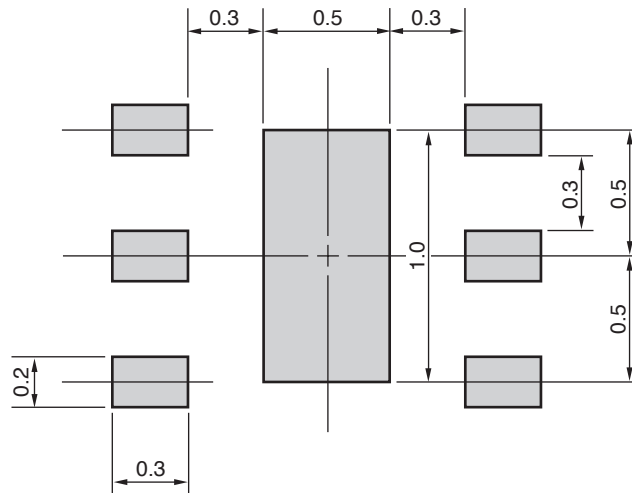
**Remark 1.** The graphs indicate nominal characteristics.

- 2.** Marker1 : 2.45 GHz
- Marker2 : 2.40 GHz
- Marker3 : 2.50 GHz
- Marker4 : 4.90 GHz

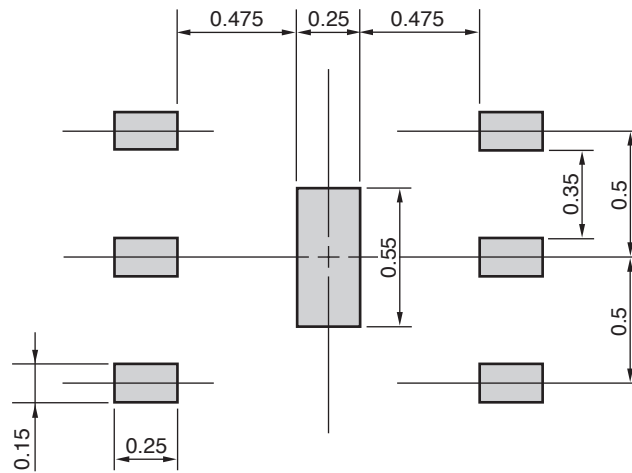
MOUNTING PAD AND SOLDER MASK LAYOUT DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)

MOUNTING PAD



SOLDER MASK



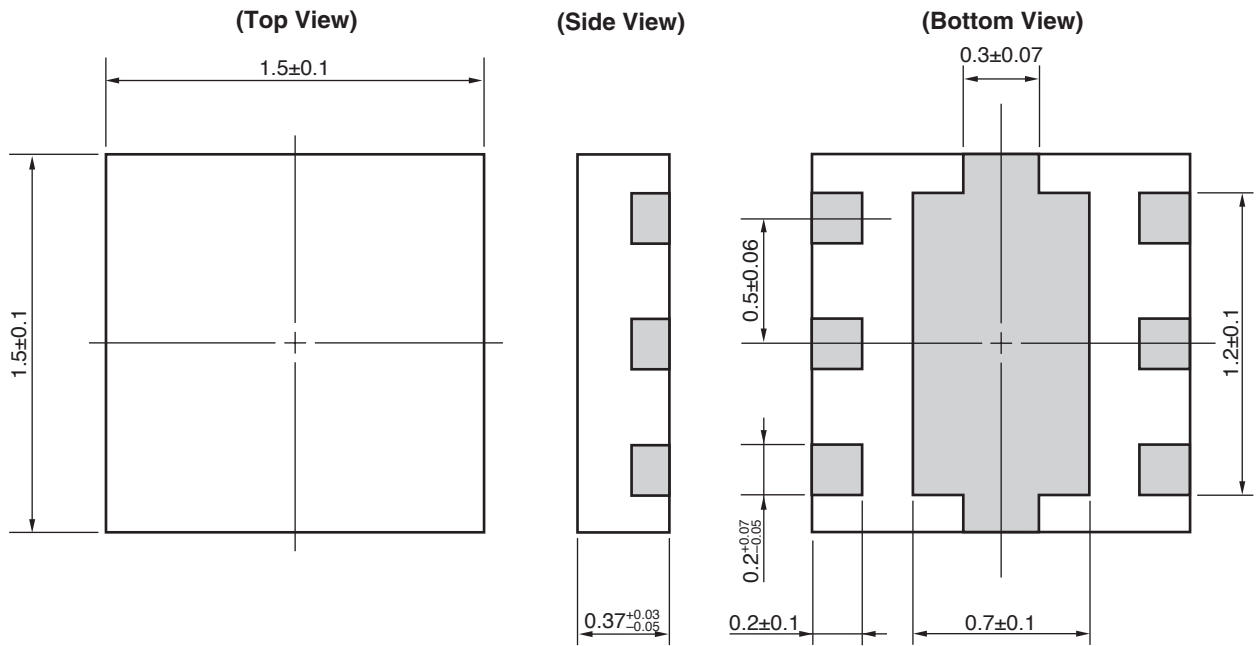
Solder thickness : 0.08 mm

**Remark** The mounting pad and solder mask layouts in this document are for reference only.



**PACKAGE DIMENSIONS**

**6-PIN PLASTIC TSON (UNIT: mm)**



**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution Do not use different soldering methods together (except for partial heating).**

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		-A	-AZ
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Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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